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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	ATTORNEY DOCKET NO. CONFIRMATION NO.	
10/664,875	09/22/2003	Naoteru Matsubara	65933-044 4231		
McDERMOTT	7590 12/18/2006 T, WILL & EMERY	EXAMINER			
600 13th Street, N.W.			IM, JUNGHWA M		
Washington, DC 20005-3096			ART UNIT	PAPER NUMBER	
			2811		
SHORTENED STATUTOR	RY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE		
3 MC	ONTHS	12/18/2006	PAPER		

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

		Application	on No.	Applicant(s)				
		10/664,87	75	MATSUBARA ET AL.				
Office Action Summary		Examiner		Art Unit				
		Junghwa N	И. lm	2811				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply								
THE MA - Extensio after SIX - If the per - If NO per - Failure to Any reply	TENED STATUTORY PERIOD FOR REFULING DATE OF THIS COMMUNICATION in softime may be available under the provisions of 37 CFR (6) MONTHS from the mailing date of this communication. From the mailing date of this communication, and for reply specified above is less than thirty (30) days, a region for reply is specified above, the maximum statutory period for reply within the set or extended period for reply will, by statut received by the Office later than three months after the material term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no evereply within the statuted will apply and will tute, cause the applicant.	ent, however, may a reply be time story minimum of thirty (30) days Il expire SIX (6) MONTHS from to ication to become ABANDONE	ely filed will be considered timely the mailing date of this co (35 U.S.C. § 133).	mmunication.			
Status								
2a)□ Th 3)□ Si	esponsive to communication(s) filed on <u>9/1</u> his action is FINAL . 2b) The specific time this application is in condition for allow used in accordance with the practice unde	his action is no wance except	for formal matters, pro		merits is			
Disposition of Claims								
4a) 5)□ CI 6)☑ CI 7)□ CI	 4) Claim(s) 1-22 is/are pending in the application. 4a) Of the above claim(s) 6-17 is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 1-5 and 18-22 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement. 							
Application	Papers							
10)⊠ The Ap Re	e specification is objected to by the Examine drawing(s) filed on 22 September 2003 is plicant may not request that any objection to the placement drawing sheet(s) including the correspond or declaration is objected to by the	is/are: a) 🔯 ache drawing(s) be ection is require	e held in abeyance. See ed if the drawing(s) is obj	37 CFR 1.85(a). ected to. See 37 CF	R 1.121(d).			
Priority und	ler 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received.								
			·	• •				
2) Notice of 3) Informati	References Cited (PTO-892) Draftsperson's Patent Drawing Review (PTO-948) on Disclosure Statement(s) (PTO-1449 or PTO/SB/0 o(s)/Mail Date <u>9/2006</u> .	08)	4) Interview Summary (Paper No(s)/Mail Da 5) Notice of Informal Pa 6) Other:	•	-152)			

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on September 18, 2006 has been entered.

Claim Objections

Claims 4 and 21 are objected to because of the following informalities: The term "second dielectric Films" in claims 4 and 23 should be -- second dielectric films--.

Appropriate correction is required.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-5 and 18-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gates et al. (US Pat. 6,603,204), hereinafter Gates in view of Ma et al. (US Pat. 6,764,810), hereinafter Ma.

Regarding claims 1 and 18, Fig. 8 of Gates shows a semiconductor device comprising:

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a semiconductor substrate [50];

a multilayered film including a first dielectric film [54'], an etching stopper [56'] and a second dielectric film [58'] stacked on said semiconductor substrate in this order; and

a via plug [a narrow portion of the metal layer 74 in the layer 54'] and a metal interconnect [a wide portion of the metal layer 74 in the layer 58'], which is formed on the via plug, formed in said multilayered film, wherein

the dielectric constant [k] of said etching stopper is larger than that of said first and second dielectric films (k=1.4-3.5 for the first and second dielectric films, k=1.1-5.5 for etching stopper; col. 4, lines 9-64).

Fig. 8 of Gates shows most aspects of the instant invention except "the upper surface of said etching stopper is located under the upper surface level of said metal interconnect, the under surface of said etching stopper is located over the under surface level of said metal interconnect, and the under surface of said metal interconnect is located inside the first dielectric film."

Figure 1H of Ma shows a metal interconnect [a wider portion of the trench 20] wherein the upper surface of the etching stopper [14; col. 5, lines 57-59] is located under the upper surface level of said metal interconnect, the under surface of said etching stopper is located over the under surface level of said metal interconnect, and the under surface of said metal interconnect is located inside the first dielectric film [12].

It would have been obvious to one of ordinary skill in the art at the time of the invention was made to incorporate the teachings of Ma into the device of Gates in order to have the upper surface of the etching stopper located under the upper surface level of said metal interconnect, the under surface of the etching stopper located over the under surface level of the metal

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interconnect, and the under surface of the metal interconnect located inside the first dielectric film to reduce a problem caused by residual masking material.

Regarding claims 2 and 19, Gates discloses the semiconductor device wherein the dielectric constant [k=1.1-5.5] of said etching stopper is less than or equal to 5 (col. 4, lines 60-64).

Regarding claims 3, 4, 20 and 21, Gates discloses the semiconductor device wherein the dielectric constant of said etching stopper is larger than or equal to a summation of 2 and the dielectric constant of either one of the dielectric constants [k=1.4-3.5] of said first and second dielectric films (col. 4, lines 15-20).

Regarding claims 5 and 22, Gates discloses said metal interconnect includes copper as a constituting element (col. 7, lines 30-35).

Response to Arguments

Applicant's arguments with respect to pending claims have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Junghwa M. Im whose telephone number is (571) 272-1655. The examiner can normally be reached on MON.-FRI. 8:30AM-5:00PM.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Richard T. Elms can be reached on (571) 272-1869. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Junghwa M. Im

Examiner

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jmi

12/9/2006